

**REMARKS**

Claims 1-11 are pending in this application. Claims 8-11 are withdrawn from consideration. By this Amendment, claim 1 is amended. No new matter has been added.

In paragraph 1, on page 2 of the Office Action, claims 1-7 are rejected under 35 U.S.C. §102(b) as being anticipated by Kunitomo et al. (Kunitomo), U.S. Patent No. 5,550,408. The rejection is respectfully traversed.

Applicant's invention of claim 1 calls for a method of manufacturing an electric device, the method comprising forming an external terminal on an interconnect pattern formed on a substrate; subsequently mounting a chip component on the substrate face up, the chip component having an electrode on a first surface of the chip component opposite to a second surface facing the substrate; and forming an interconnect for electrically connecting the electrode and the interconnect pattern at a temperature lower than a melting point of the external terminal. Kunitomo fails to disclose or suggest all of these features.


Contrary to the Office Action assertion, Kunitomo fails to disclose or suggest subsequently mounting a chip component on the substrate face up, the chip component having an electrode on a first surface of the chip component opposite to a second surface facing the substrate. Kunitomo only teaches mounting a chip component on the substrate face down (col. 5, lines 54-60). The process steps of manufacturing the semiconductor device according to Kunitomo include this "flip-chip" method by which the semiconductor chip is mounted on the insulating substrate with its top surface facing downward (Fig. 7 and col. 7, lines 43-51). Applicant, on the other hand, does not mount the semiconductor chip on the substrate facing downward. Rather, claim 1 recites mounting a chip component on the substrate face up. Thus, because Kunitomo does not disclose or suggest mounting a chip component on the substrate face up, as in claim 1, Kunitomo fails to disclose or suggest all of the features of Applicant's claim 1.

Further, because claims 2-7 incorporate the features of claim 1, Kunitomo fails to disclose or suggest the features of any of these claims for the foregoing reasons and for the additional features recited therein. Therefore, it is respectfully requested the rejection be withdrawn.

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of claims 1-7 are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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